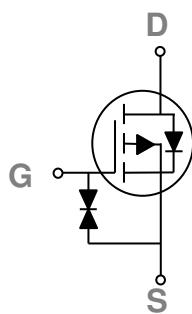
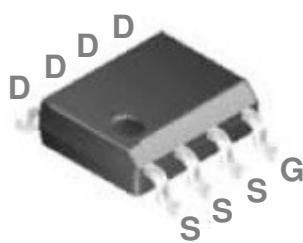


### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOP8 Pin Configuration



### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	-7	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	-4.4	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	-28	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	3.2	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.026	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	60	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	38	$^\circ\text{C/W}$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-30	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =85°C	---	---	-10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±20	uA

**On Characteristics**

R <sub>DSON</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-2.5A	---	27	32	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A	---	42	52	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.2	-1.6	-2.5	V
g <sub>f</sub> s	Forward Transconductance	V <sub>DS</sub> =-10V, I <sub>D</sub> =-5A	---	5	---	S

**Dynamic and switching Characteristics**

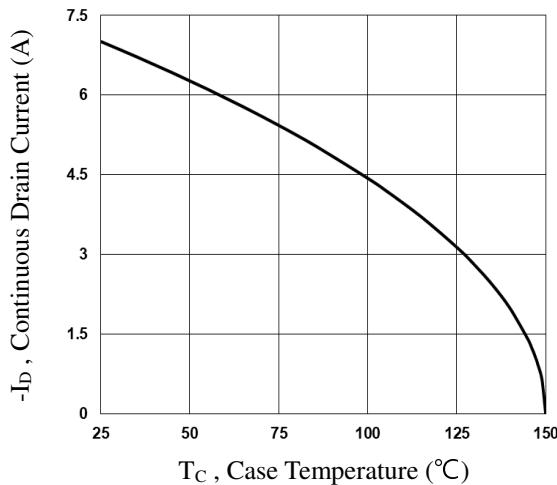
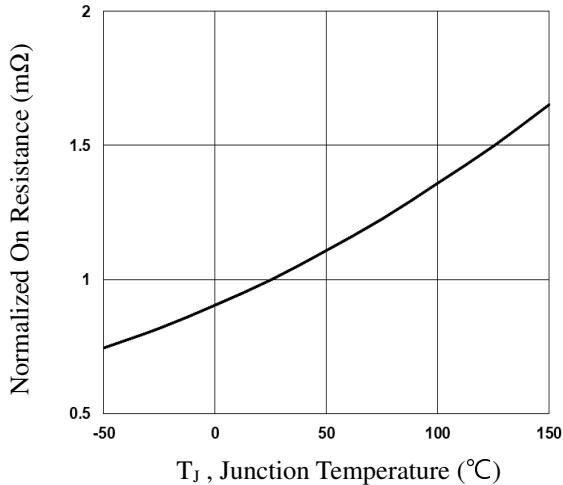
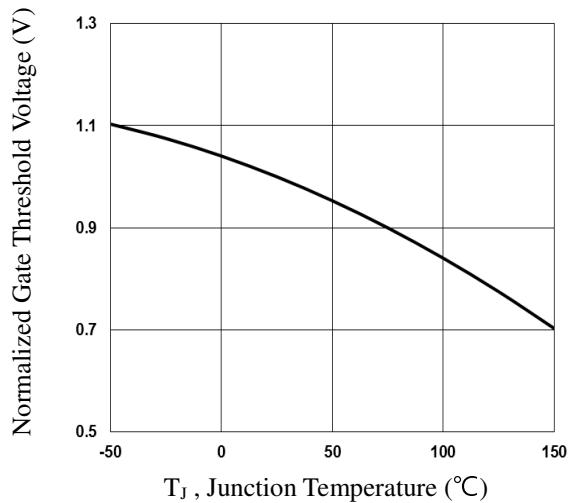
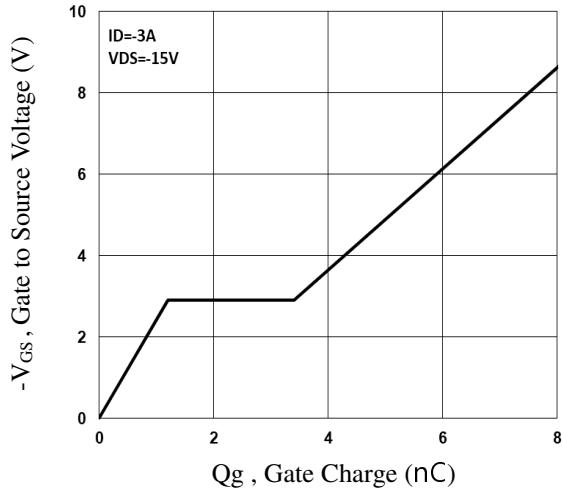
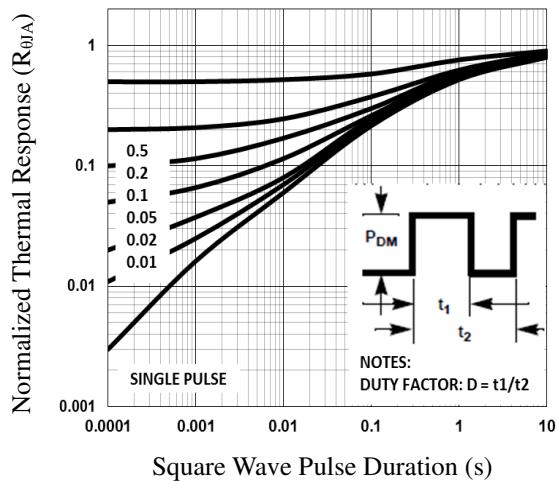
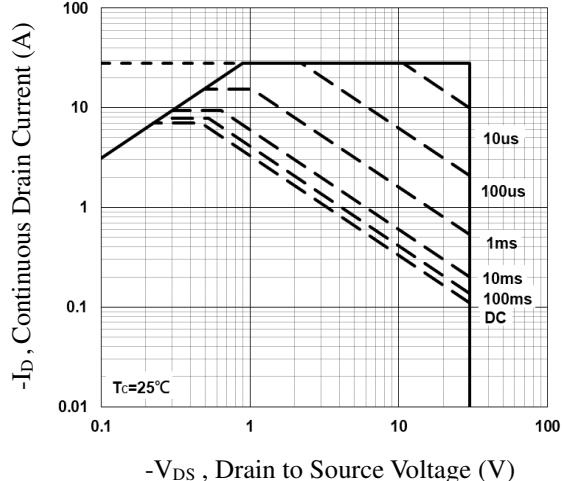
Q <sub>g</sub>	Total Gate Charge <sup>2, 3</sup>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-3A	---	9.1	14	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2, 3</sup>		---	1.2	1.8	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2, 3</sup>		---	2.2	3.3	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2, 3</sup>	V <sub>DD</sub> =-15V, V <sub>GS</sub> =-10V, R <sub>G</sub> =6Ω I <sub>D</sub> =-1A	---	9.2	18	ns
T <sub>r</sub>	Rise Time <sup>2, 3</sup>		---	28	56	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2, 3</sup>		---	68	136	
T <sub>f</sub>	Fall Time <sup>2, 3</sup>		---	36	72	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, F=1MHz	---	410	820	pF
C <sub>oss</sub>	Output Capacitance		---	120	240	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	58	116	

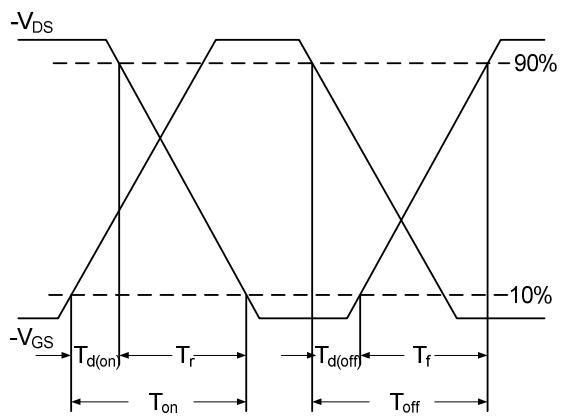
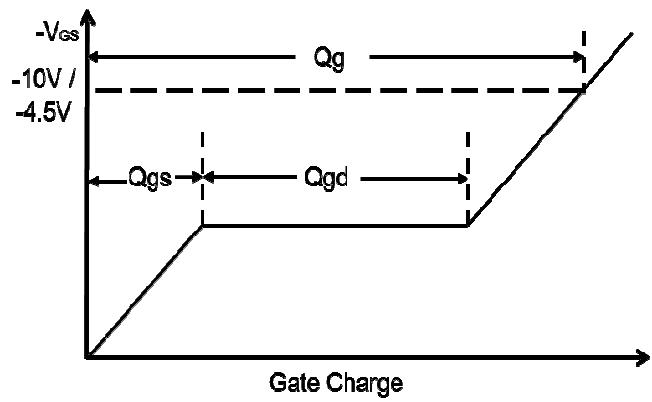
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-7	A
I <sub>SM</sub>	Pulsed Source Current		---	---	-14	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1	V
T <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =0V, I <sub>S</sub> =6.5A, di/dt=100A/μs, T <sub>J</sub> =25°C	---	185	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge		---	465	---	nC

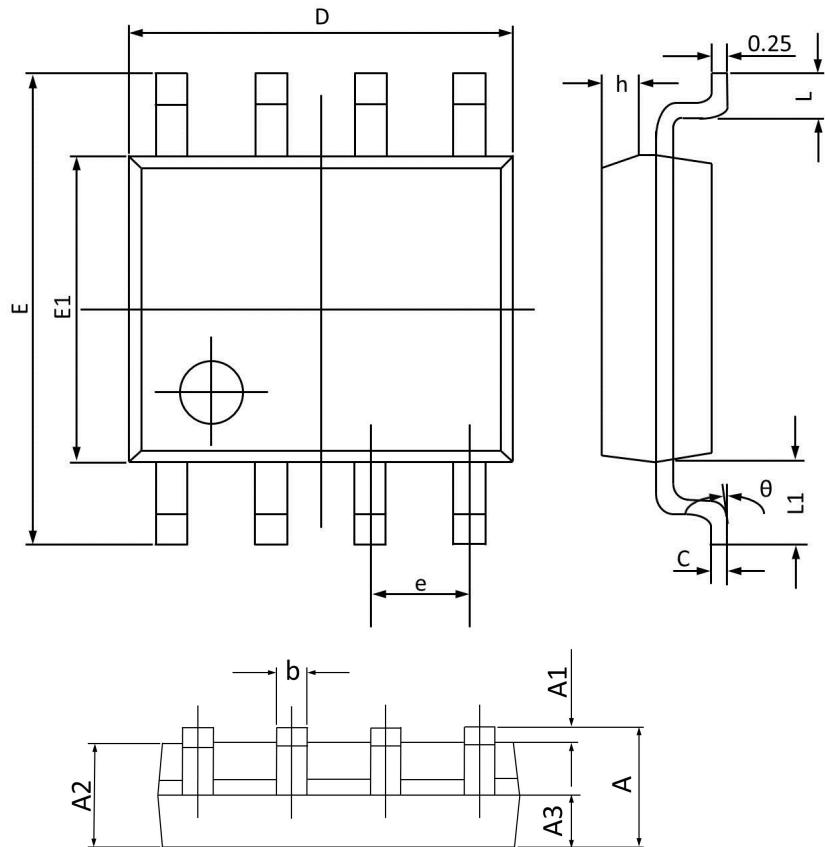
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs.  $T_C$** 

**Fig.2 Normalized RD<sub>SON</sub> vs.  $T_J$** 

**Fig.3 Normalized V<sub>th</sub> vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 Gate Charge Waveform**

## SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.250	1.650	0.049	0.065
A3	0.500	0.700	0.020	0.028
b	0.380	0.510	0.015	0.020
c	0.170	0.260	0.007	0.010
D	4.700	5.100	0.185	0.201
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.400	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°